



Docket No. RV1.PAU.53

Patent Application

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Pepe, et al.

Serial No.: 09/938,686

Filed: October 30, 2001

For: STACKABLE LAYERS
CONTAINING ENCAPSULATED
INTEGRATED CIRCUIT CHIPS
WITH ONE OR MORE
OVERLYING INTERCONNECT
LAYERS AND A METHOD OF
MAKING THE SAME

Examiner: Hung K. Vu

Group Art Unit: 2811

Irvine, California

May 15, 2003

*# 10/11/03 HKA
Rme
3/27/03*

RECEIVED
MAY 22 2003
TECHNOLOGY CENTER 2800

AMENDMENT "B" – RESPONSE TO OFFICE ACTION

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

Please enter the following amendment in response to the Office Action dated December 19, 2002. A request for a two-month extension of time and appropriate fees are enclosed. If necessary, please charge Deposit Account No. 01-1960.

IN THE TITLE

Please amend the title by replacing the title with the following: METHOD OF MAKING STACKABLE LAYERS CONTAINING ENCAPSULATED INTEGRATED CIRCUIT CHIPS WITH ONE OR MORE OVERLAYING INTERCONNECT LAYERS.